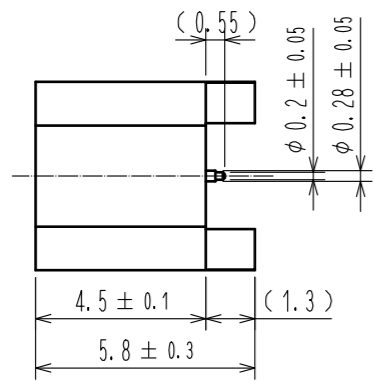
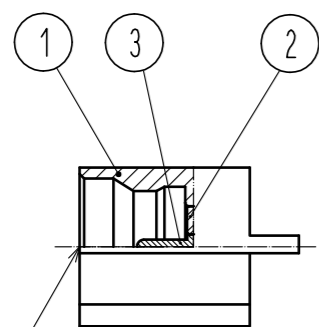
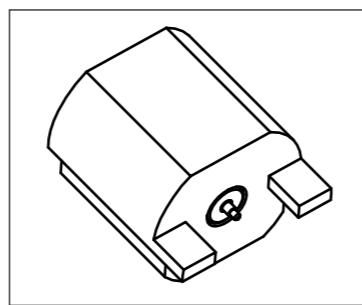


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In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

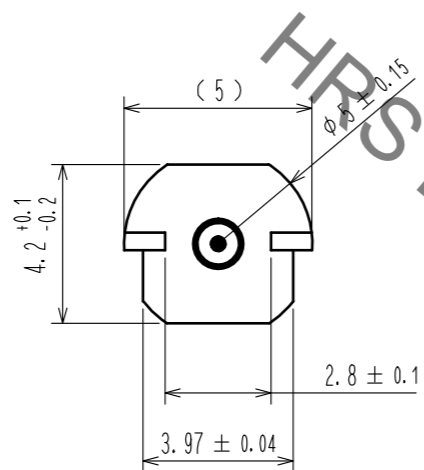
FD



PERSPECTIVE VIEW

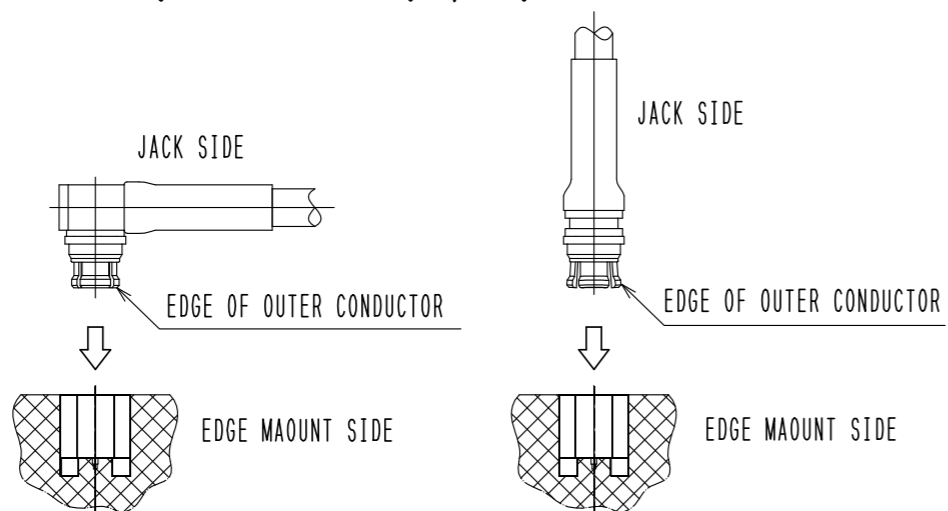


SMP Interface  
FD : Full detent



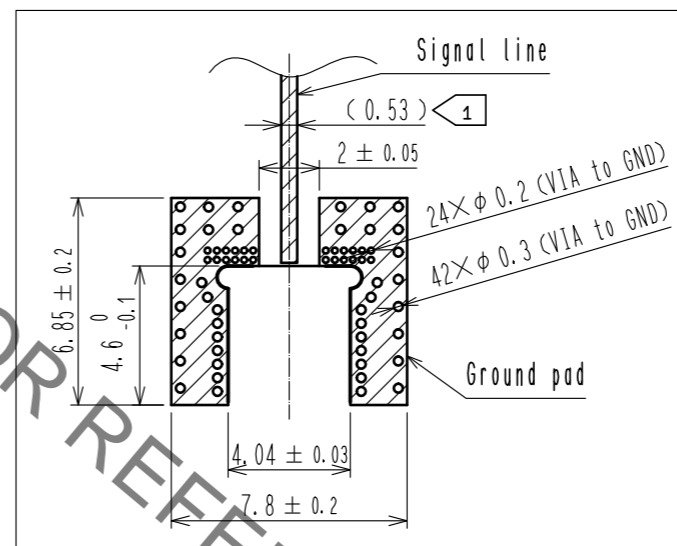
【 PRECAUTIONS FOR HANDLING 】

Insert and extract a jack as perpendicular to the mating surface as possible by aligning the mate axes between a jack and a edge mount. Do not excessively slant the connectors when inserting and extracting, because the slanting may damage the connectors in some cases.

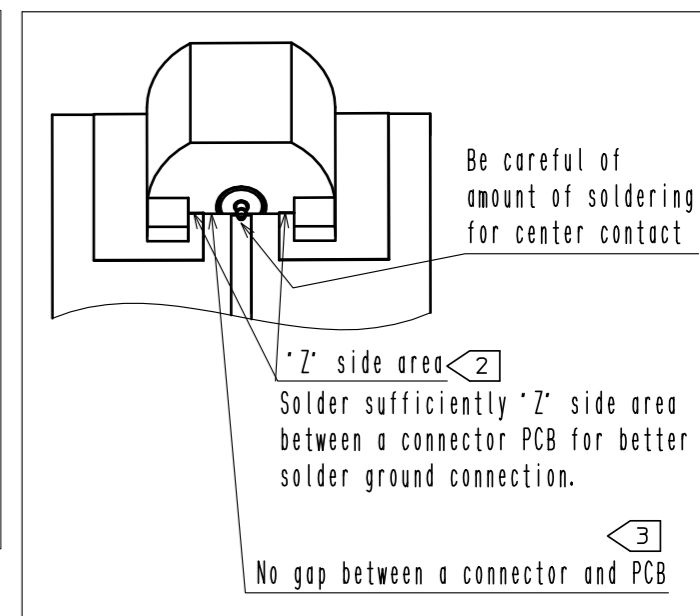


- NOTE
- The dimension of (0.53) indicated in the recommended PCB layout below is met in the condition of dielectric constant of 3.48 and thickness of 0.254. The dimension depends on the dielectric constant, thickness and layout of PCB. For better RF performance, simulation of PCB with the connector is recommended.
  - Side plating is recommended on side plane of connector mounting area of PCB as shown in the perspective view below.  
When soldering grounding, solder sufficiently a side area between a connector and PCB.  
Recommended soldering both top and bottom side of PCB as shown in the a perspective view after soldering below. Especially solder sufficiently 'Z' side area between a connector and PCB as shown in outline drawing for mounting below for better RF performance.  
In manual soldering, soldering iron bit temperature is 380 °C max. for 5 seconds max.  
When soldering center contact, be careful of amount of solder. If the width of center soldering is over the one of signal line, the RF performance would be degraded.
  - Please mount a connector on PCB without the gap between the side edge of PCB and connector for better RF performance. Recommended flat plane of side edge of PCB.

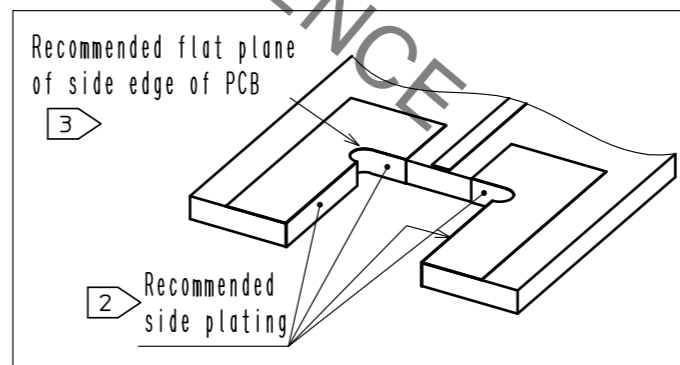
Recommended PCB Layout



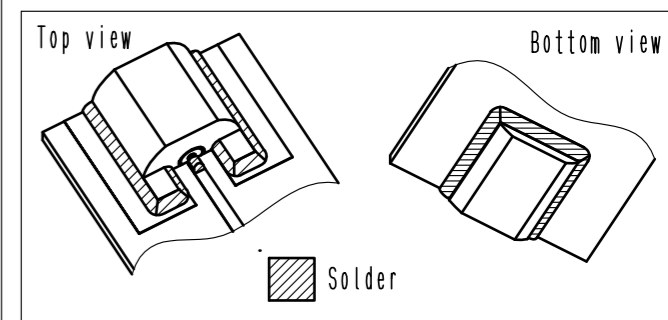
Outline drawing for mounting



Perspective view of PCB



Perspective view after soldering



2	PTFE		3	PHOSPHOR BRONZE	GOLD PLATING
1	BRASS	GOLD PLATING			
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS		SCALE	COUNT	DESCRIPTION OF REVISIONS	
mm		5 : 1		DESIGNED	CHECKED
<b>HRS</b> HIROSE ELECTRIC CO., LTD.		APPROVED : TO. KATAYAMA	18.06.08	DRAWING NO. EDC-373491-00-00	
		CHECKED : KY. SHIMIZU	18.06.08	PART NO. SMP-LPR(FD)-SMT-1	
		DESIGNED : TM. YOSHIDA	18.06.08	CODE NO. CL338-1105-0-00	
		DRAWN : TM. YOSHIDA	18.06.08		